

3EC-M3S-HTE

- ・ 于回火后之高伸率及高耐曲折特性, 等同于压延铜箔(RA)。
High Elongation and flexibility after annealing, equally with RA copper foil.
- ・ 于S面进行表面处理, 具较3EC-HTE更低的粗糙度。
Lower profile compare with 3EC-HTE because of S-side surface treatment.
- ・ 自2011年起日本、台湾和马来西亚等3地均已量产, 提供稳定的铜箔供货。
Stable supply is available because of 3-factory-production.

用途/Application

- ・ 软性电路板
/Flexible Print Board

构成/Composition



生产地点/Production Site

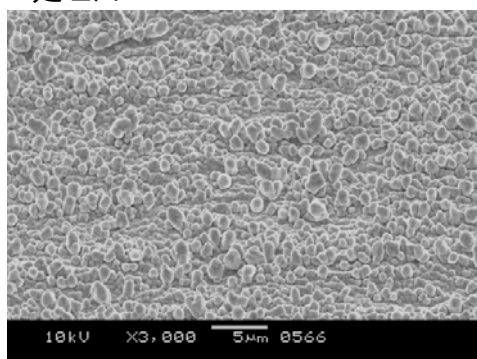
- ・ 日本/Japan
- ・ 马来西亚/Malaysia

代表性特性数据/Representative data

	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
3EC-M3S-HTE	12	107	2.5	390	6	0.8
	18	153	2.5	390	10	0.9

※上述表列为代表性数据非保证值
This is representative data, not guaranteed.

处理面/Laminate side



阻剂面/ resist side

